

ABSTRACT OF THE DISCLOSURE

A method fabricates light-emitting chips having a heat-dissipating structure to enhance its work efficiency and applications. By means of an appropriate bonding technique, the method mainly attaches an insulating, heat-dissipating substrate that has metal electrodes, to
5 a chip that has metal blocks. The module of combined chip and the heat-dissipating substrate is cut into light-emitting chips with a heat-dissipating structure to serve as the light source of light-emitting diodes.